

1. (Once Amended) An integrated circuit comprising:

at least one metal layer comprising a plurality of regions, wherein a first contiguous region comprises an area of said metal layer of at least 100 square microns and comprises a plurality of conductors to interconnect points on said integrated circuit, said conductors comprising a plurality of preferred diagonal direction conductors and at least one zag conductor, and wherein a second contiguous region comprises a plurality of conductors such that at least fifty (50) percent of said conductors are arranged in a preferred direction other than said preferred diagonal direction;

    said preferred diagonal direction conductors comprising at least fifty (50) percent of said conductors in said first region and being deposited in a preferred diagonal direction that forms a Euclidean angle relative to the boundaries of the integrated circuit; and

    said at least one zag conductor being deposited in a Manhattan direction and being coupled to one of said preferred diagonal direction conductors so as to interconnect points on said integrated circuit using at least one zag conductor and at least one preferred diagonal direction conductor.

11. (Once Amended) An integrated circuit comprising:

    a plurality of metal layers with each metal layer comprising a plurality of conductors to interconnect points on the integrated circuit, at least fifty (50) percent of said conductors on a first metal layer being deposited in a first preferred diagonal direction, wherein said first preferred diagonal direction defines a direction that forms a Euclidean

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angle relative to the boundaries of the integrated circuit, for at least fifty percent of conductors on said first metal layer;

at least fifty (50) percent of said conductors on a second metal layer arranged in a second preferred diagonal direction, wherein said second preferred diagonal direction defines a direction, different than said first preferred diagonal direction, that forms a Euclidean angle relative to the boundaries of the integrated circuit; and

at least one zig conductor, coupled to a conductor deposited in a first diagonal direction, said zig conductor being deposited in a Manhattan direction so as to interconnect points on said integrated circuit using at least one zig conductor and at least one conductor arranged in said first preferred diagonal direction.

12. (Once Amended) The integrated circuit of claim 1, wherein said first preferred diagonal direction comprises plus 45 degrees and said second preferred diagonal direction comprises minus 45 degrees relative to the boundaries of said integrated circuit.

13. (Once Amended) The integrated circuit of claim 1, wherein said first preferred diagonal direction comprises minus 45 degrees and said second preferred diagonal direction comprises plus 45 degrees relative to the boundaries of said integrated circuit.

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15. (Once Amended) The integrated circuit of claim 1, wherein said first preferred diagonal direction comprises plus 60 degrees and said second preferred diagonal direction comprises minus 60 degrees relative to the boundaries of said integrated circuit.

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16. (Once Amended) The integrated circuit of claim 1, wherein said first preferred diagonal direction comprises minus 60 degrees and said second preferred diagonal direction comprises plus 60 degrees relative to the boundaries of said integrated circuit.

17. (Once Amended) The integrated circuit of claim 1, wherein said first preferred diagonal direction comprises plus 30 degrees and said second preferred diagonal direction comprises minus 30 degrees relative to the boundaries of said integrated circuit.

18. (Once Amended) The integrated circuit of claim 1, wherein said first preferred diagonal direction comprises minus 30 degrees and said second preferred diagonal direction comprises plus 30 degrees relative to the boundaries of said integrated circuit.

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